



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



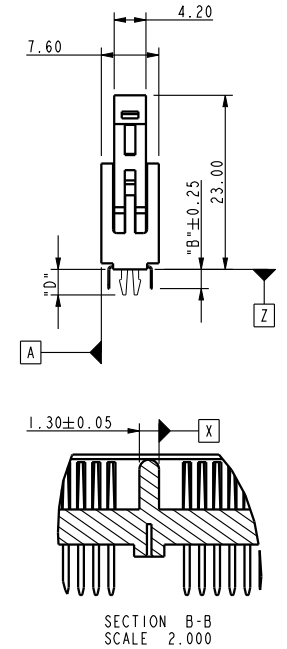
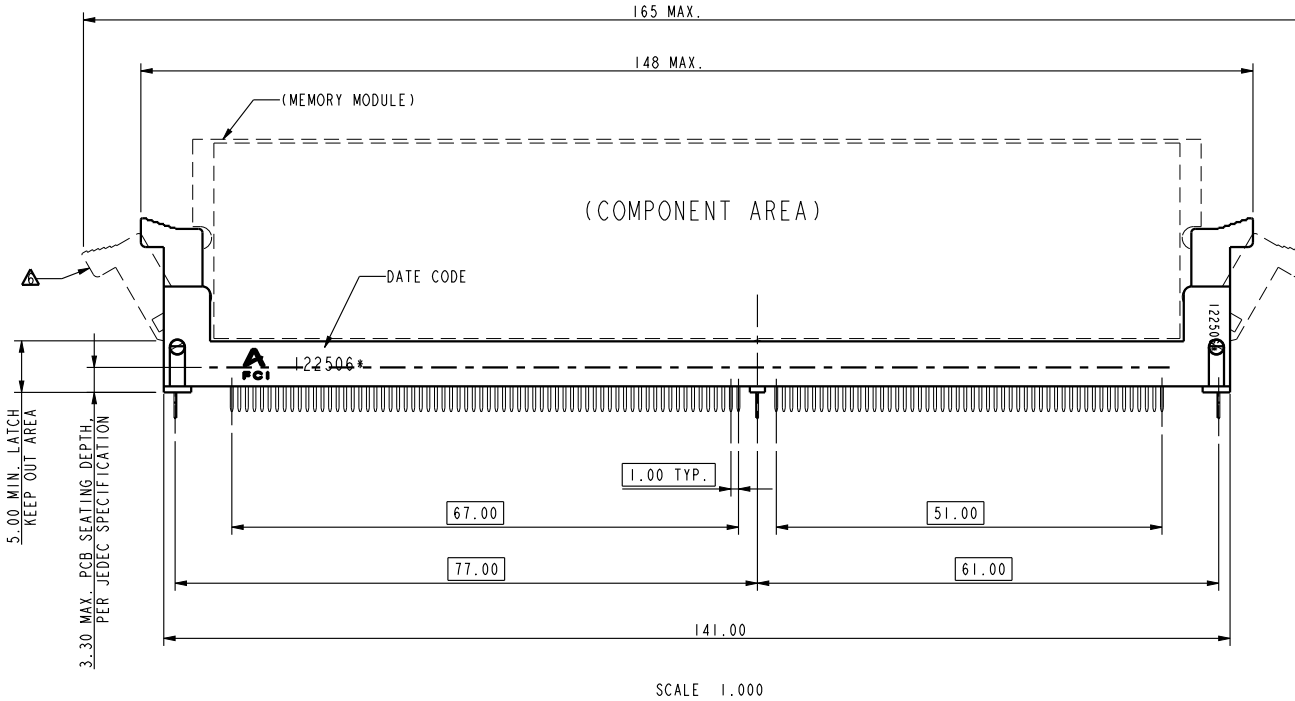
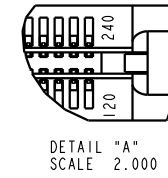
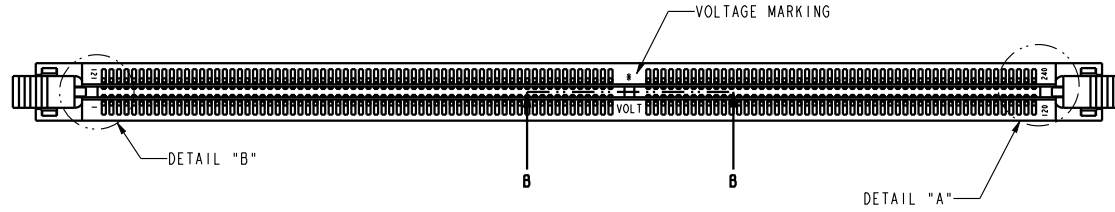
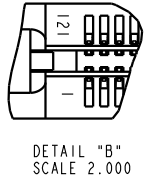
Contact us

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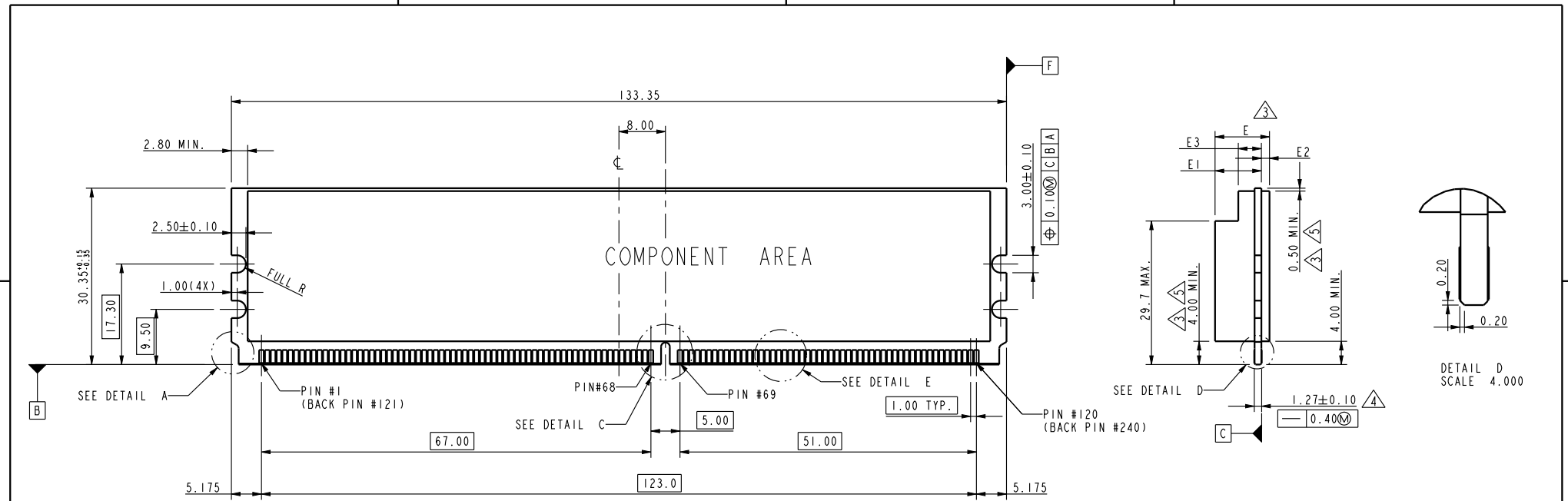
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

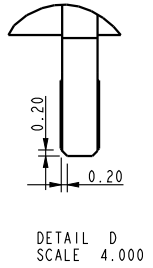
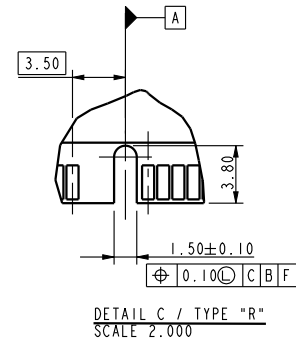
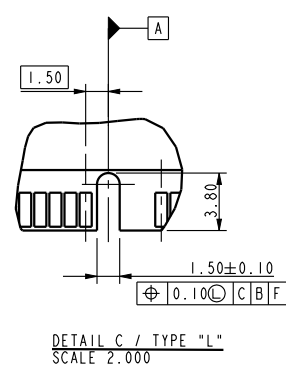
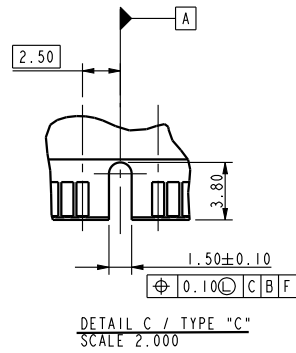
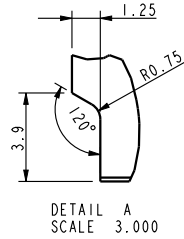
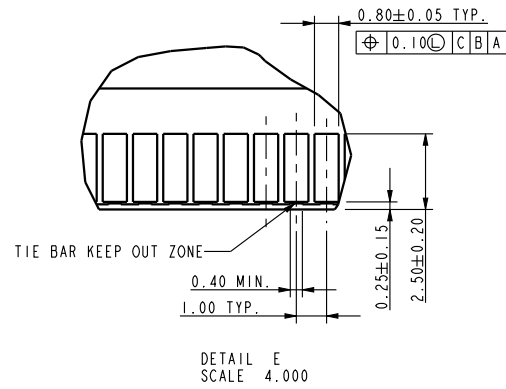




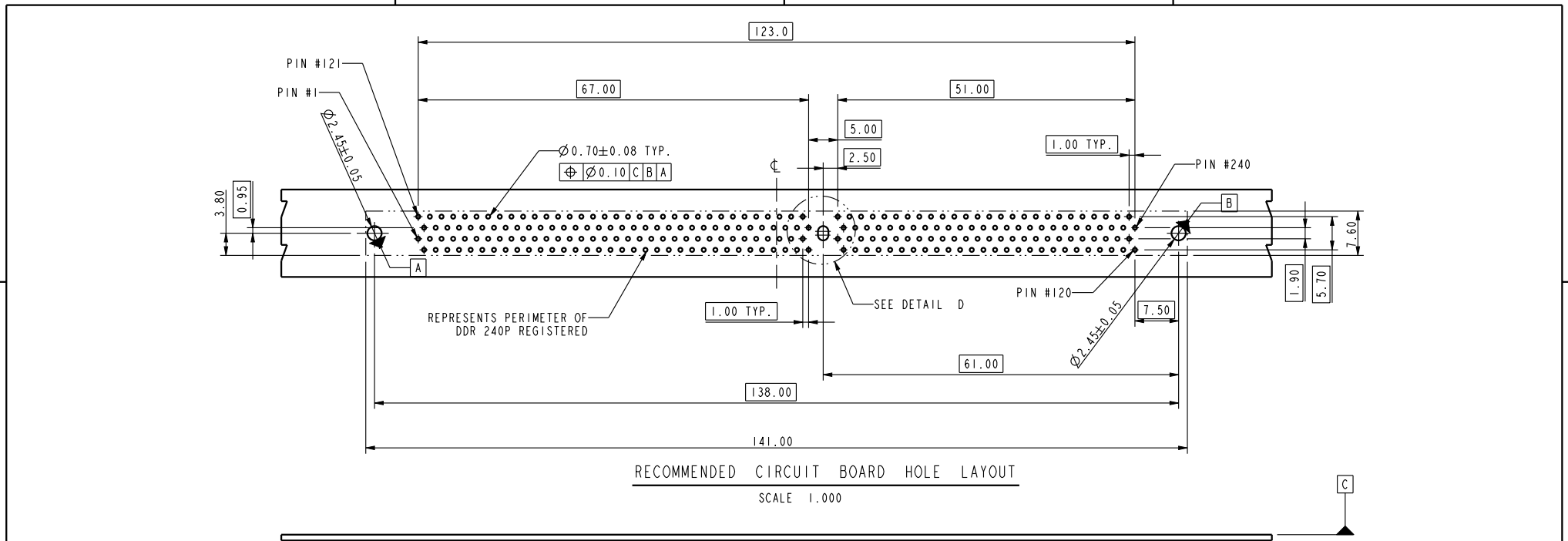
spec ref *		dr Rick Bian 2010/07/08		projection 	MM ←→	size	scale
tolerance std		eng Jeny Ren 2018/01/26				A4	0.500
ISO 406 ISO 1101		chr -				ecn no ELX-DG-28708-1	
surface		appr Nickor Zuo 2018/01/29		product family		rel level Released	
ISO 1302	linear	0.X	±0.38	Amphenol FCi	title	10057443	
		0.XX	±0.15				
	angular	0°	±2°				
cat. no.		* Product - Customer Drw		sheet 1 of 4			



RECOMMENDED MODULE LAYOUT (PER JEDEC MO-256)

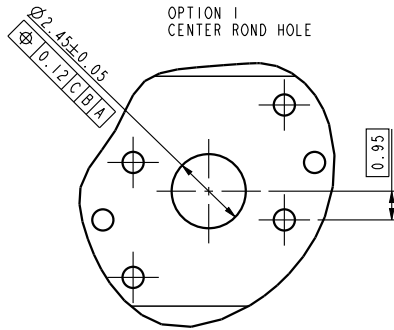


spec ref	*	dr	Rick Bian	2010/07/08	projection	MM	size	A4	scale	0.500
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Jeny Ren	2018/01/26		↔	ecn no	ELX-DG-28708-1		
ISO 406		chr	-	-			rel level	Released		
ISO 1101		appr	Nickor Zuo	2018/01/29	product family		rev	D		
surface	linear	Amphenol FCI	title		DDRII 240P FBDIMM		dwg no	10057443		
	angular		cat. no.		Product - Customer Drw			sheet 2 of 4		
	0.X	±0.38								
	0.XX	±0.15								
	0.XXX	±0.13								
	0°	±2°								

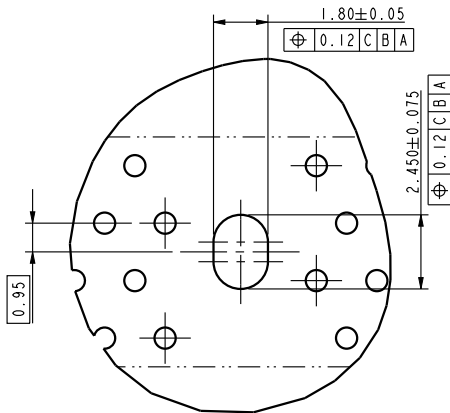


RECOMMENDED CIRCUIT BOARD HOLE LAYOUT
SCALE 1.000

DETAIL D
SCALE 4.000



OPTION 2
CENTER SLOT



tolerances unless otherwise specified		
linear	.X	±0.38
	.XX	±0.25
	.XXX	±0.13
angles	X°	±2°

dr	Rick Bian	2010/07/08	projection 	MM 	size	A4	scale	0.500
eng	Jeny Ren	2018/01/26			ecn no	ELX-DG-28708-1		
chr	-	-			rel level	Released		
appr	Nickor Zuo	2018/01/29	product family		rev		10057443	
Amphenol FCi		title			DDR II 240P FBDIMM		dwg no	
					SMALL HEAD SOCKET		D	
cat. no.		Product - Customer Drw			sheet 3 of 4			

10057443-□ □ □ □ □

STYLE : MECHANICAL KEYING

- 1 : 1.8 VOLT. W/TYPE "C"
- 2 : 2.5 VOLT. W/TYPE "L"
- 3 : X.X VOLT. W/TYPE "R"

METAL CLIP:
(WITH NI 1.27 um MIN. PLATING)

- 1 : WITH METAL CLIP + DIM."D"-3.05
- 2 : WITH METAL CLIP + DIM."D"-3.56
- 3 : WITH METAL CLIP + DIM."D"-3.43

TAIL LENGTH

CODE	DIM. "B"	PCB THICKNESS
0	2.54	1.47 mm (0.058")
1	2.67	1.60 mm (0.063")
2	3.18	2.36 mm (0.093")
3	4.00	3.18 mm (0.125")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2	15 u"(0.38um) MIN. GOLD	100u"(2.54um) MIN. TIN/LEAD	50u"(1.27um) MIN. NICKEL OVERALL
3	30u"(0.76um) MIN. GOLD		
4	3u"(0.076um) MIN. GOLD	100u"(2.54um) MIN. 100% TIN	50u"(1.27um) MIN. NICKEL OVERALL
7LF	15u"(0.38um) MIN. GOLD		
8LF	30u"(0.76um) MIN. GOLD	100u"(2.54um) MIN. 100% TIN	90u"(2.29um) MIN. NICKEL OVERALL
9LF	3u"(0.076um) MIN. GOLD		
2N	15 u"(0.38um) MIN. GOLD	100u"(2.54um) MIN. TIN/LEAD	90u"(2.29um) MIN. NICKEL OVERALL
3N	30 u"(0.76um) MIN. GOLD		
4N	3 u"(0.076um) MIN. GOLD	100u"(2.54um) MIN. 100% TIN	90u"(2.29um) MIN. NICKEL OVERALL
7NLF	15 u"(0.38um) MIN. GOLD		
8NLF	30 u"(0.76um) MIN. GOLD	100u"(2.54um) MIN. 100% TIN	90u"(2.29um) MIN. NICKEL OVERALL
9NLF	3 u"(0.076um) MIN. GOLD		

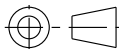

NOTE:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS,
GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS,
GLASS FILLED UL 94V-0 RATED.
TERMINAL : COPPER ALLOY.
METAL CLIP: COPPER ALLOY.
2. PRODUCT SPECIFICATION: GS-12-300.
- △ DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON ONE OR BOTH SIDES.
- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR) MEALIZATION STRAIGHTNESS CALLOUT APPLIES TO ZONE DEFINED BY THE 4.00 CONTACT AREA DIMENSION FOR THE ENTIRE LENGTH OF 133.35.
- △ BOARD OF COMPONENT AREA.
- △ LATCH DESIGN INCLUDES COMPLEMENTARY FEATURE TO ACCOMMODATE MODULE END NOTCHES AS DEFIND IN DETAIL A OF P.2 AND AS SPECIFIED IN MO-256.
7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMP. FOR 10 SECONDS IN A WAVE SOLDER APPLICATION
9. 10057443-XXXX(X)LF SERIES ARE FOR LEAD-FREE OPTIONS.
10. DATE CODE:XXXXX* MEANS MONTH/DAY/YEAR.
"*" MEANS PRODUCTION LINE CODE.

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 1 : BLUE HOUSING + IVORY EJECTOR
- 2 : BLACK HOUSING + BLACK EJECTOR

TYPE R	X.X VOTAGLE	6.80	1.40	2.80	8.20	6.80	3.00	4.40	9.80
TYPE L	2.5 VOLTAGE	6.80	1.40	2.80	8.20	6.80	3.00	4.40	9.80
TYPE C	1.8 VOLTAGE	6.80	1.40	2.80	8.20	6.80	3.00	4.40	9.80
SUB KEY POS. #1	DESCRIPTION	DIM. E1 MAX.	DIM. E2 MAX.	DIM. E3 MAX.	DIM. E MAX.	DIM. E1 MAX.	DIM. E2 MAX.	DIM. E3 MAX.	DIM. E MAX.
					TYPE 1		TYPE 2		

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chr	-	-			rel level	Released			
appr	Nickor Zuo	2018/01/29	product family		rev	D			
Amphenol FCI		title			DDR11 240P FBDIMM		dwg no		10057443
		SMALL HEAD SOCKET							
cat. no.		Product - Customer Drw			sheet		4 of 4		